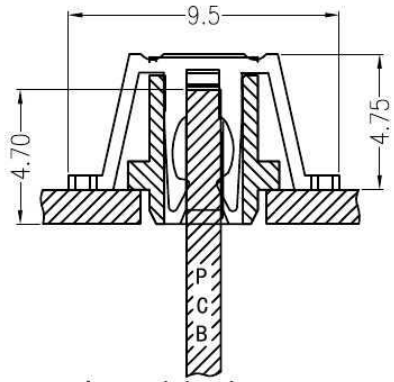
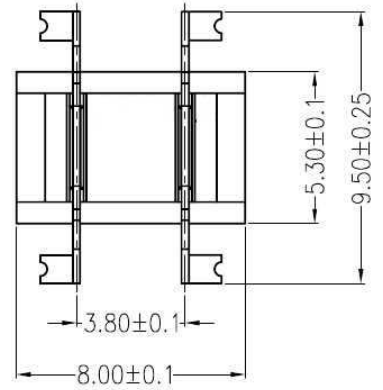
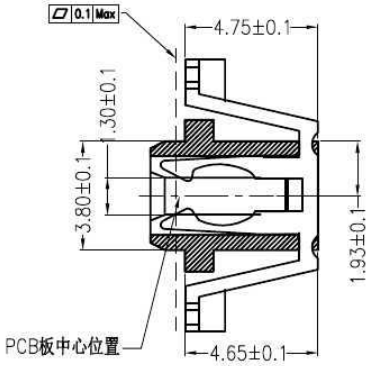
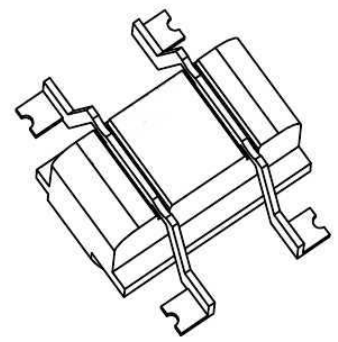


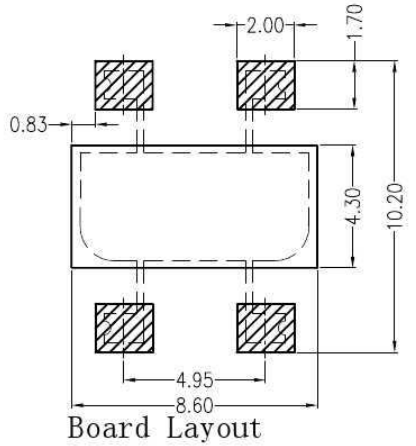
REV	DESCRIPTION	DESIGN	DATE
A0	Release	李润	2015.09.19



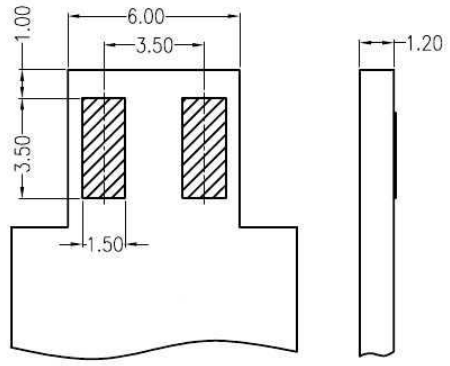
Assembly Layout



Main Specifications
 Thickness: 1.2mm
 Contact resistance: ≤20mOhm
 Insulation resistance: ≥1000MOhm
 Rated voltage: 250V AC DC
 Rated current: 1.0A AC DC
 Withstand Voltage: 1000V AC/minute
 Temperature Range: -40°C --- +120°C



Board Layout



Mating PCB detail

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C				
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: --	
			3.8mmPITCH 180°WAFER SMT TYPE	
X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2°	APPD: 邵敬和	DWG NO.:	
.XX±0.25	.XX±1°	CHKD: 田峰		
--	--	DR: 蒋建银	SCALE: 1 : 1	SHEET: 1 / 1
UNITS: mm				